

ALPHA[®] OM338-T Solder Paste

Ultra-Fine Feature, Lead-Free

DESCRIPTION

ALPHA OM-338-T is a lead-free, no-clean solder paste designed for a broad range of applications. **ALPHA OM-338-T**'s broad processing window is designed to minimize transition concerns from tin/lead to lead free solder paste. This material is engineered to deliver the comparable performance to a tin lead process.* **ALPHA OM-338-T** yields excellent print capability performance across various board designs and, particularly, with ultra fine feature repeatability (11 mil Squares) and high throughput applications.

Outstanding reflow process window delivers good soldering on CuOSP with excellent coalescence on a broad range of deposit sizes, excellent random solder ball resistance and mid-chip solder ball performance. **ALPHA OM-338-T** is formulated to deliver exceptional visual joint cosmetics. Additionally, **ALPHA OM-338-T**'s capability of IPC Class III for voiding and ROL0 IPC classifications ensures maximum long-term product reliability

* Although the appearance of these lead-free alloys will be different to that of tin-lead, the mechanical reliability is equal to or greater than with that of tin-lead or tin-lead-silver.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

FEATURES & BENEFITS

- Maximizes reflow yield for lead-free processing, allowing full alloy coalescence at circular dimensions as small as 0.25mm (0.010") with 0.100mm (4mil) stencil thickness.
- Excellent print consistency with high process capability index across all board designs.
- Print speeds of up to 200mm/s (8in/s), enabling a fast print cycle time and a high throughput.
- Wide reflow profile window with good solderability on various board / component finishes.
- Excellent solder and flux cosmetics after reflow soldering
- Reduction in random solderballing levels, minimizing rework and increasing first time yield
- Meets highest IPC 7095 voiding performance classification of Class III.
- Excellent reliability properties, halide-free material
- Compatible with either nitrogen or air reflow

PRODUCT INFORMATION

<u>Alloys:</u>	SAC305 (96.5%Sn/3.0%Ag/0.5%Cu) SAC387 (95.5%Sn/3.8%Ag/0.7%Cu) SAC396 (95.5%Sn/3.9%Ag/0.6%Cu) SAC405 (95.5%Sn/4.0%Ag/0.5%Cu) SACX® Plus 0307, SACX Plus 0807
<u>Powder Size:</u>	Type 3, Type 4
<u>Residues:</u>	Approximately 5% by (w/w)
<u>Packaging Sizes:</u>	500 gram jars, 6 in & 12in cartridges, and 10cc and 30cc dispense syringes.
<u>Flux Gel:</u>	ALPHA OM-338 Flux Gel is available in 10cc and 30cc syringes for rework applications.
<u>Lead Free:</u>	RoHS Directive EU/2015/863; amending Annex II of 2011/65/EU

Note: For other alloys, powder size and packaging sizes, contact your local Alpha Sales Office.

TECHNICAL DATA

Category	Results	Procedures/Remarks
Chemical Properties		
Activity Level	ROL0	IPC J-STD-004A IPC J-STD-004B
Halide Content	Halide free (by titration)	IPC J-STD-004A IPC J-STD-004B
Halogen Test	Pass , Zero Halogen - No halogen intentionally added	EN14582, by oxygen bomb combustion, Non-detectable (ND) at < 50 ppm
Ag Chromate Test	Pass	IPC J-STD-004A
Copper Mirror Test	Pass	IPC J-STD-004A
Copper Corrosion Test	Pass (No evidence of Corrosion)	IPC J-STD-004A
Electrical Properties		
SIR (IPC 7 days @ 85° C /85% RH)	Pass	IPC J-STD-004A

Category	Results	Procedures/Remarks
SIR	Pass	IPC J-STD-004B
(IPC 7 days @ 40 °C /90% RH)		
SIR (Bellcore 96 hrs @ 35 °C /85%RH)	Pass	Bellcore GR78-CORE
Electromigration (Bellcore 96 hrs @ 65 °C /85%RH 10V 500 hrs)	Pass	Bellcore GR78-CORE
Physical Properties (Using 88.5% Metal, Type #3 Powder)		
Color	Clear, Colorless Flux Residue	
Tack Force vs. Humidity (t=8 hours)	Pass , Change of <1 g/mm ² over 24 hours at 25% and 75 % Relative Humidity	IPC J-STD-005
Tack Force vs. Time	Pass , Change of <1 g/mm ² over 24 hours at 25% and 75 % Relative Humidity	IPC J-STD-005
	Pass , Change of <10% when stored at 25±2 °C and 50±10% relative humidity	JIS Z 3284, Annex 9
Solderball	Acceptable (SAC 305 and SAC405 alloys)	IPC J-STD-005
	Pass , Class 2, 1 hour and 72 hour	DIN Standard 32 513, 4.4
Spread	Pass	JIS Z 3197: 1999 8.3.1.1
Flux Tackiness Test	Pass	DIN 32513 Talc Test
Slump	Pass	IPC J-STD-005 (10 min, 150 °C)
	Pass	DIN Standard 32 513, 5.3
	Pass	JIS Z 3284:1994 Annex 8
Stencil Life	8 hours	@ 50%RH, 23 °C (74 °F)

PROCESSING GUIDELINES

Handling	Printing	Reflow	Cleaning
<ul style="list-style-type: none"> Refrigerate to guarantee stability @ 0 to 10 °C(32 to 50 °F) Shelf life of refrigerated paste is six months from the manufacturing date. Paste can be stored for 2 weeks at room temperatures up to 25 °C (77 °F) prior to use. When refrigerated, warm-up of paste container to room temperature for a minimum of 4 hours. Paste must be ≥19 °C (66 °F) before processing. Verify paste temperature with a thermometer to ensure paste is at 19 °C (66 °F) or greater before setup. Printing can be performed at temperatures up to 29 °C (84 °F). Do not remove worked paste from stencil and mix with unused paste in jar. This will alter rheology of unused paste. 	<p><u>Stencil:</u> Recommend ALPHA CUT or ALPHA FORM stencils @ 0.100 to 0.150 mm (4 to 6 mil) thick for 0.4 to 0.5 mm (0.016in or 0.020in) pitch. Stencil design is subject to many process variables. Contact your local Alpha stencil site for advice.</p> <p><u>Squeegee:</u> Metal (recommended)</p> <p><u>Pressure:</u> 0.16 to 0.34 kg/cm of squeegee length (0.9 to 2.0 lbs./inch).</p> <p><u>Speed:</u> 25 to 200mm per second (1 to 8 inches per second).</p> <p><u>Stencil Release Speed:</u> 5 to 20mm/sec.</p> <p><u>Paste Roll:</u> 1.5 to 2.0 cm diameter and make additions when roll reaches 1-cm (0.4") diameter (min). Max roll size will depend upon blade.</p> <p><u>Print Pump Head:</u> Passes MPM 2000 print compaction and DEK ProFlow™ testing.</p>	<p><u>ATMOSPHERE:</u> Clean-dry air or nitrogen atmosphere.</p> <p><u>PROFILE (SAC Alloys):</u> A straight ramp profile @ 0.8 °C to 1.7°C per second ramp rate is recommended (TAL 35 to 90 sec and peak 232 to 250 °C).⁽¹⁾ Higher density assemblies may require preheating with within the profile and may be accomplished as follows:</p> <ul style="list-style-type: none"> From 40 °C to Liquidus: Between 2min 30 sec. and 4 min. (optimum⁽²⁾ is 3 min.) From 170 °C to Liquidus: Between 45 sec. and 75 sec. (optimum⁽²⁾ is 1 min.) From 130 °C to Liquidus: Between 1min. 20 sec. and 2 min. 15 sec. (optimum⁽²⁾ is 1min. 30 sec.) Time above liquidus: Between 30 sec. and 90 sec. (optimum⁽²⁾ is 45 sec. to 70 sec.) <p>Note 2: Refer to component and board supplier data for thermal properties at elevated temperatures. Lower peak temperatures require longer TAL for improved joint cosmetics.</p> <p>Note 3: OM-338-T is designed to work under a wide range of reflow profiles in order to find the optimum profile for your process. This can be achieved by balancing:</p> <ol style="list-style-type: none"> (1) Minimum Delta T's (depending on board mass and thermal oven characteristics) (2) Maximum Reflow Yield (includes voiding, cosmetics, solder balling, etc.) (3) Minimum Stress and Overheat for Components and Boards (refer to suppliers' guidelines and specifications.) <p>Contact your local Alpha Customer Technical Service representative for further details.</p>	<p>ALPHA OM-338-T residue is designed to remain on the board after reflow. If reflowed residue cleaning is required, ALPHA BC-2200 aqueous cleaner is recommended. For solvent cleaning, agitation for 5 min in the following cleaners is recommended:</p> <ul style="list-style-type: none"> - ALPHA SM-110E - ATRON® AC 205 (Zestron) <p>Misprints and stencil cleaning may be done with ALPHA SM-110E, ALPHA SM-440, ALPHA BC-2200, and ZESTRON® SD 301 cleaners.</p>

Note 4: The processing guidelines recommended and typical reflow profiles presented were tested in the lab with acceptable performance. Optimization to each board application should still be carried out by users to ensure best results.

REFLOW PROFILES

Figure 1: Typical Soak Reflow Profile for SAC Alloys

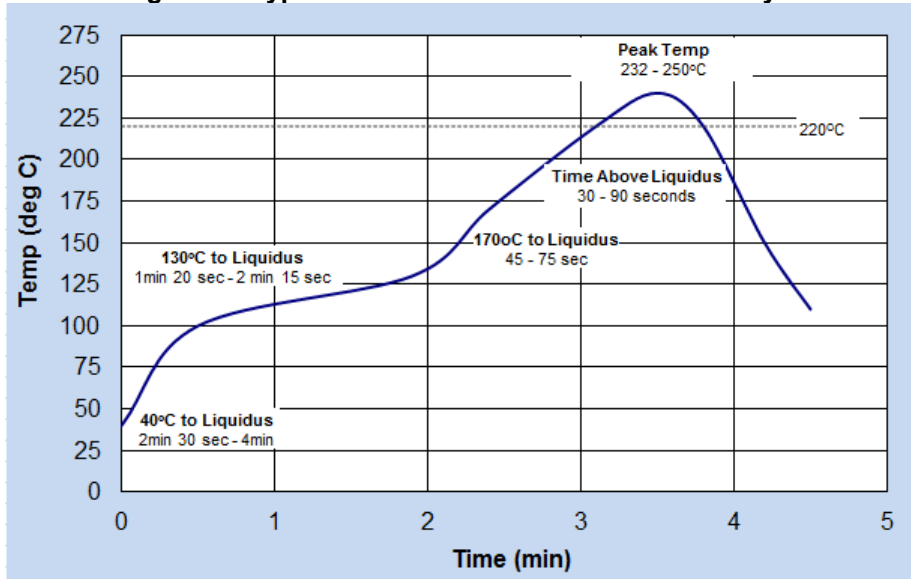
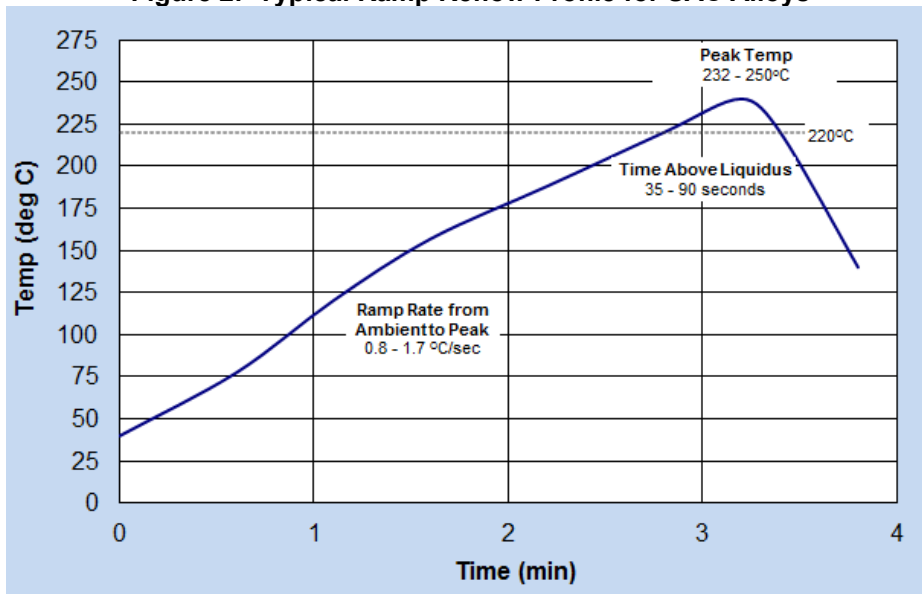


Figure 2: Typical Ramp Reflow Profile for SAC Alloys



RECYCLING SERVICES

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams.

Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area or [link here](#).



SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at MacdermidAlpha.com/assembly-solutions/knowledge-base.**

CONTACT INFORMATION

To confirm this document is the most recent version, please contact Assembly@MacDermidAlpha.com

www.macdermidalpha.com

<p>North America 109 Corporate Blvd. South Plainfield, NJ 07080, USA 1.800.367.5460</p>	<p>Europe Unit 2, Genesis Business Park Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400</p>	<p>Asia 8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong 852.3190.3100</p>
--	--	---

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, indirect, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "(R)" and "TM" are registered trademarks or trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.